DATA SHEET

74LVC574

Octal D-type flip-flop;
positive edge-trigger (3-State)

Product specification
Supersedes data of February 1996
IC24 Data Handbook

1997 Mar 18

Philips
Semiconductors

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Octal D-type flip-flop; positive edge-trigger (3-State) 74LVC574

FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 8-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Output drive capability 50Ω transmission lines @ 85°C

DESCRIPTION

The 74LVC574 is a high-performance low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families. Inputs can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LV574 is an octal D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-State outputs for bus oriented applications. A clock (CP) and an output enable ($\overline{OE}$) input are common to all flip-flops.

The eight flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition.

When $\overline{OE}$ is LOW, the contents of the eight flip-flops is available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance OFF-state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops. The '574' is functionally identical to the '374' but the '374' has a different pin arrangement.

QUICK REFERENCE DATA

GND = 0V; T_{amb} = 25°C; $t_r = t_f \leq 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay CP to Qn	C_L = 50pF V_{CC} = 3.3V	4.8	ns
f_{max}	Maximum clock frequency	C_L = 50pF V_{CC} = 3.3V	150	MHz
C_I	Input capacitance		5.0	pF
C_{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	28	pF

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW)
   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz; C_L = output load capacity in pF;
   f_o = output frequency in MHz; V_{CC} = supply voltage in V;
   $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.
2. The condition is V_I = GND to V_{CC}

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic SO	–40°C to +85°C	74LVC574 D	74LVC574 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +85°C	74LVC574 DB	74LVC574 DB	SOT339-1
20-Pin Plastic TSSOP Type I	–40°C to +85°C	74LVC574 PW	74LVC574PW DH	SOT360-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	$\overline{OE}$	Output enabled input (active LOW)
2, 3, 4, 5, 6, 7, 8, 9	D0–D7	Data inputs
19, 18, 17, 16, 15, 14, 13, 12	Q0–Q7	3-State flip-flop outputs
10	GND	Ground (0V)
11	CP	Clock input (LOW-to-HIGH, edge-triggered)
20	VCC	Positive supply voltage

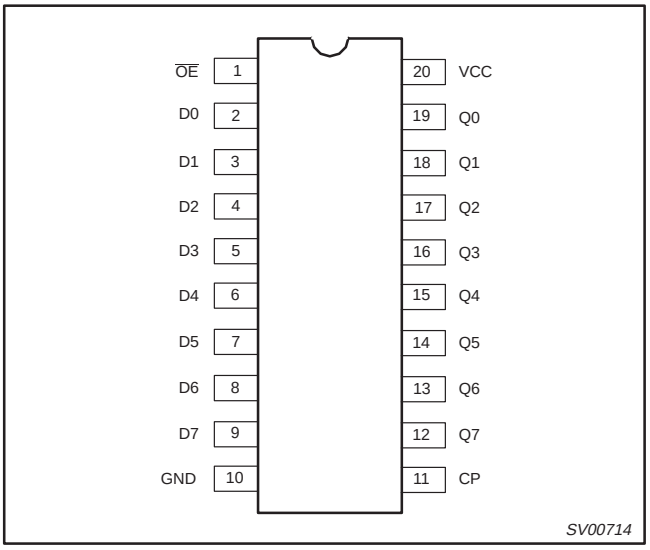
FUNCTION TABLE

OPERATING MODES	INPUTS			INTERNAL FLIP-FLOPS	OUTPUTS
	$\overline{OE}$	CP	Dn		Q0 to Q7
Load and read register	L L	↑ ↑	l h	L H	L H
Load register and disable outputs	H H	↑ ↑	l h	L H	Z Z

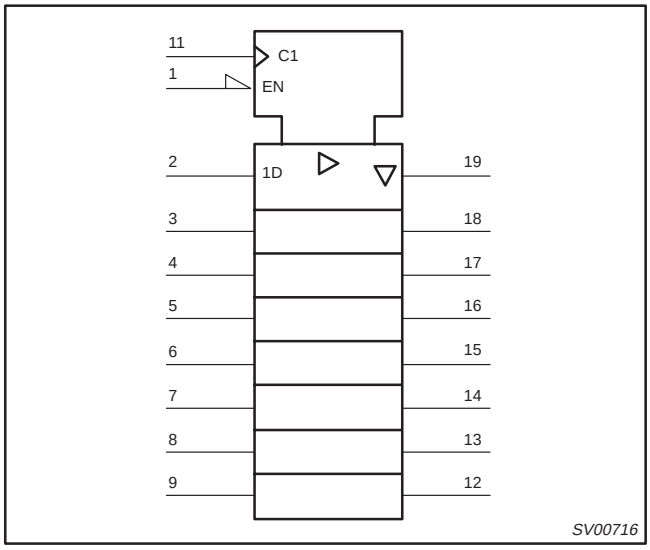
H = HIGH voltage level
h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition
L = LOW voltage level
l = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition
Z = High impedance OFF-state
↑ = LOW–to–HIGH clock transition

Octal D-type flip-flop; positive edge-trigger (3-State) 74LVC574

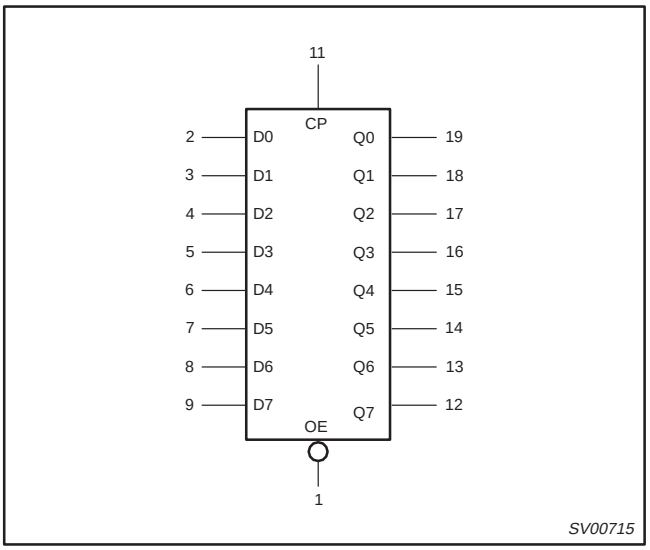
PIN CONFIGURATION



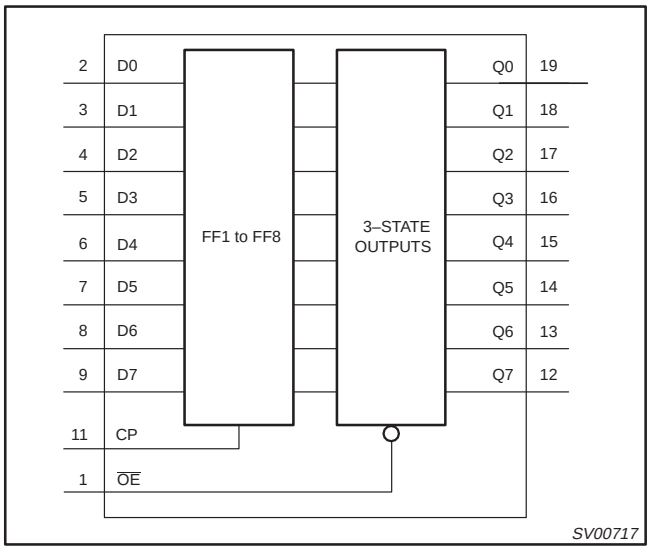
LOGIC SYMBOL (IEEE/IEC)



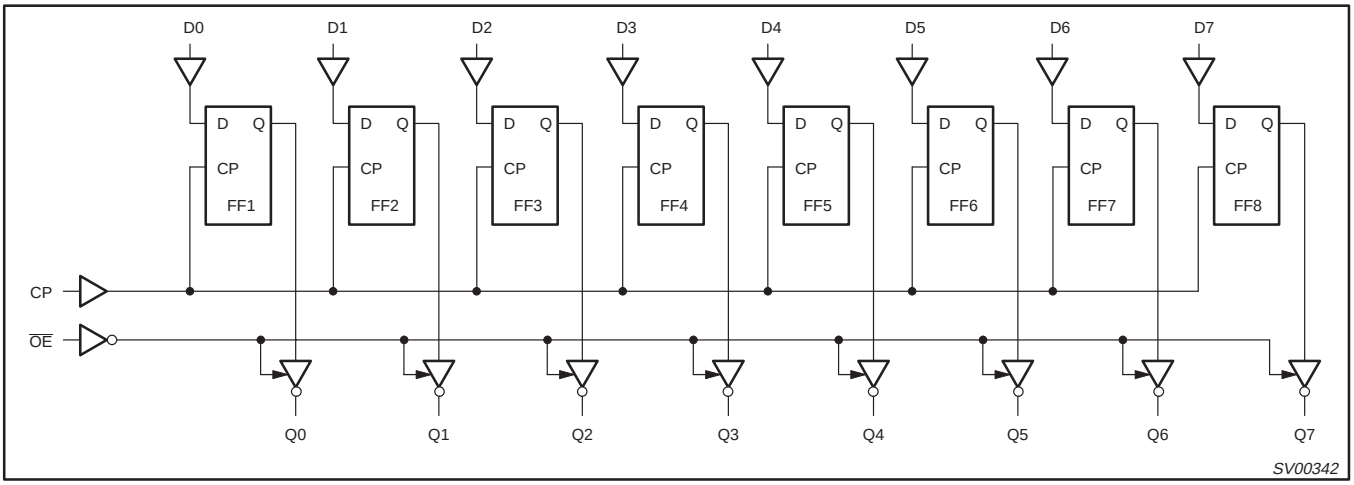
LOGIC SYMBOL



FUNCTIONAL DIAGRAM



LOGIC DIAGRAM



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
V_{CC}	DC supply voltage (for max. speed performance)		2.7	3.6	V
V_{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
V_I	DC input voltage range		0	5.5	V
$V_{I/O}$	DC input voltage range for I/Os		0	V_{CC}	V
V_O	DC output voltage range		0	V_{CC}	V
T_{amb}	Operating free-air temperature range		–40	+85	°C
t_r, t_f	Input rise and fall times	V_{CC} = 1.2 to 2.7V V_{CC} = 2.7 to 3.6V	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS[1]

In accordance with the Absolute Maximum Rating System (IEC 134).
Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +6.5	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage	Note 2	–0.5 to +5.5	V
$V_{I/O}$	DC input voltage range for I/Os		–0.5 to V_{CC} +0.5	V
I_{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
V_{OUT}	DC output voltage	Note 2	–0.5 to V_{CC} +0.5	V
I_{OUT}	DC output source or sink current	V_O = 0 to V_{CC}	±50	mA
I_{GND}, I_{CC}	DC V_{CC} or GND current		±100	mA
T_{stg}	Storage temperature range		–60 to +150	°C
P_{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	 above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	 500 500	mW

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP[1]	MAX	
V_{IH}	HIGH level Input voltage	V_{CC} = 1.2V	V_{CC}			V
		V_{CC} = 2.7 to 3.6V	2.0			
V_{IL}	LOW level Input voltage	V_{CC} = 1.2V			GND	V
		V_{CC} = 2.7 to 3.6V			0.8	
V_{OH}	HIGH level output voltage	V_{CC} = 2.7V; V_I = V_{IH} or V_{IL}; I_O = –12mA	V_{CC} – 0.5			V
		V_{CC} = 3.0V; V_I = V_{IH} or V_{IL}; I_O = –100µA	V_{CC} – 0.2	V_{CC}		
		V_{CC} = 3.0V; V_I = V_{IH} or V_{IL}; I_O = –12mA	V_{CC} – 0.6			
		V_{CC} = 3.0V; V_I = V_{IH} or V_{IL}; I_O = –24mA	V_{CC} – 1.0			
V_{OL}	LOW level output voltage	V_{CC} = 2.7V; V_I = V_{IH} or V_{IL}; I_O = 12mA			0.40	V
		V_{CC} = 3.0V; V_I = V_{IH} or V_{IL}; I_O = 100µA		0	0.20	
		V_{CC} = 3.0V; V_I = V_{IH} or V_{IL}; I_O = 24mA			0.55	
I_I	Input leakage current	V_{CC} = 3.6V; V_I = 5.5V or GND Not for I/O pins		±0.1	±5	µA
I_{IHZ}/I_{ILZ}	Input current for common I/O pins	V_{CC} = 3.6V; V_I = V_{CC} or GND		±0.1	±15	µA
I_{OZ}	3-State output OFF-state current	V_{CC} = 3.6V; V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND		0.1	±10	µA
I_{CC}	Quiescent supply current	V_{CC} = 3.6V; V_I = V_{CC} or GND; I_O = 0		0.1	20	µA
ΔI_{CC}	Additional quiescent supply current per input pin	V_{CC} = 2.7V to 3.6V; V_I = V_{CC} –0.6V; I_O = 0		5	500	µA

NOTE:
1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

AC CHARACTERISTICS

GND = 0 V; $t_r = t_f \leq 2.5$ ns; C_L = 50 pF

SYMBOL	PARAMETER	WAVEFORM	LIMITS						UNIT
			V_{CC} = 3.3V ±0.3V			V_{CC} = 2.7V		V_{CC} = 1.2V	
			MIN	TYP[1]	MAX	MIN	MAX	TYP	
t_{PHL}/t_{PLH}	Propagation delay CP to Qn	Figures 1, 4	1.5	4.8	8.5	1.5	9.5	21	ns
t_{PZH}/t_{PZL}	3-State output enable time $\overline{OE}$ to Qn	Figures 2, 4	1.5	4.0	7.5	1.5	8.0	17	ns
t_{PHZ}/t_{PLZ}	3-State output disable time $\overline{OE}$ to Qn	Figures 2, 4	1.5	3.5	6.0	1.5	6.5	8.0	ns
t_W	Clock pulse width HIGH or LOW	Figure 1	–	3.0	–	–	–	–	ns
t_{su}	Set-up time Dn to CP	Figure 3	1.0	0.3	–	1.0	–	–	ns
t_h	Hold time Dn to CP	Figure 3	1.0	–0.2	–	1.0	–	–	ns
f_{max}	Maximum clock pulse frequency	Figure 1	75	150	–	–	–	–	MHz

NOTE:
1. These typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

AC WAVEFORMS

V_M = 1.5V at $V_{CC} \geq$ 2.7V
V_M = 0.5V * V_{CC} at V_{CC} < 2.7V
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_X = V_{OL}$ + 0.3V at $V_{CC} \geq$ 2.7V; $V_X = V_{OL}$ + 0.1V_{CC} at V_{CC} < 2.7V
$V_Y = V_{OH}$ – 0.3V at $V_{CC} \geq$ 2.7V; $V_Y = V_{OH}$ – 0.1V_{CC} at V_{CC} < 2.7V

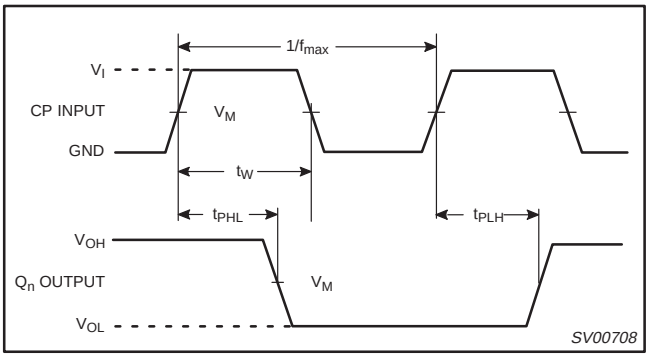


Figure 1. Clock (CP) to output (Qn) propagation delays, the clock pulse (CP), and the maximum clock pulse frequency

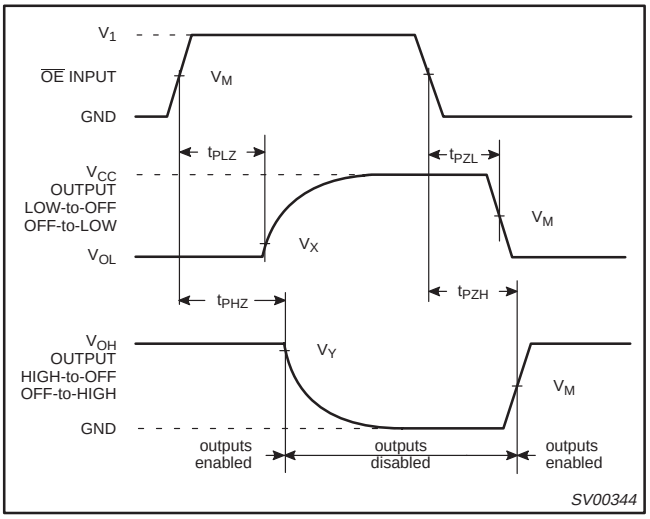


Figure 2. 3-State enable and disable times

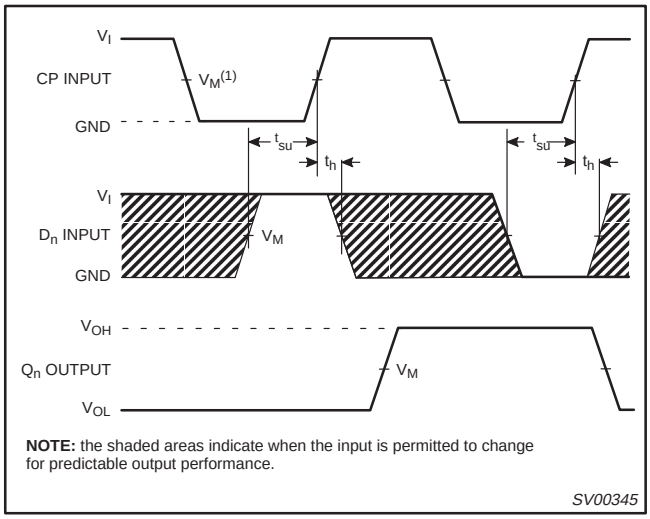
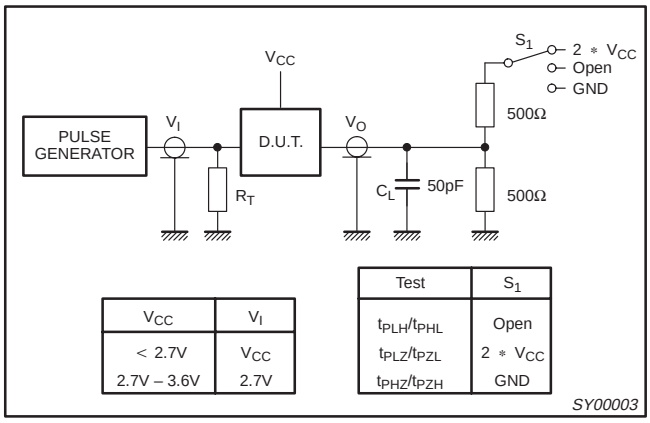


Figure 3. Data set-up and hold times for the Dn input to the CP input

TEST CIRCUIT

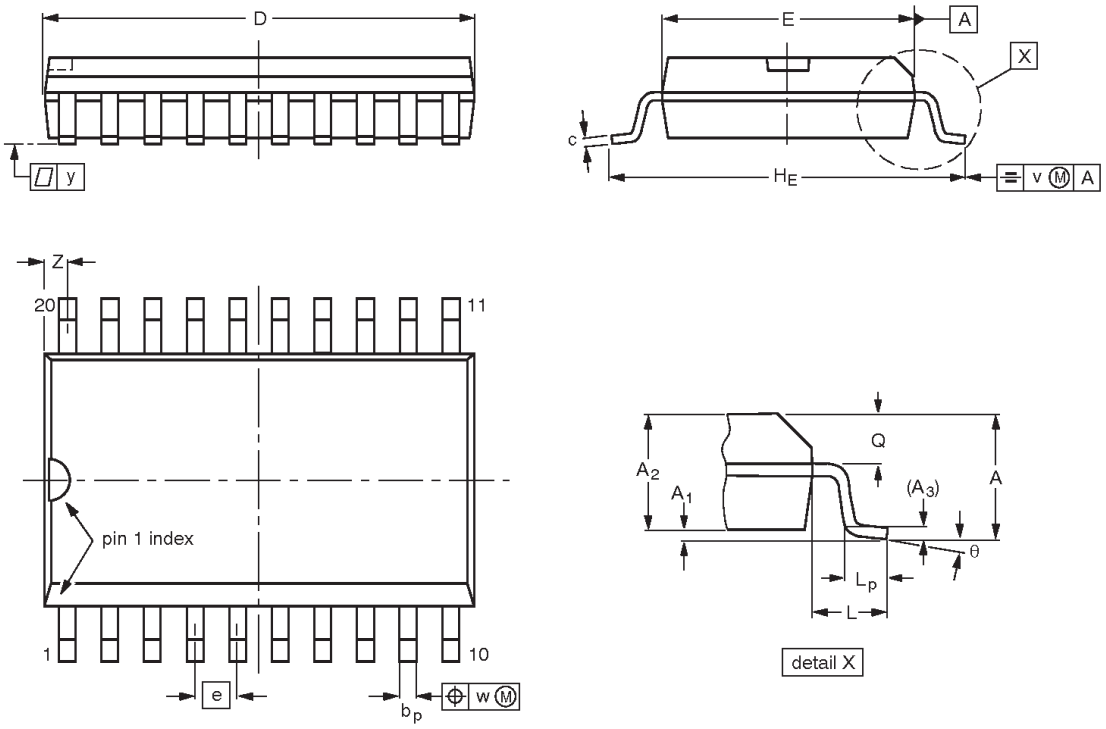


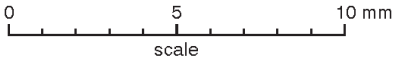
V_{CC}	V_I
< 2.7V	V_{CC}
2.7V – 3.6V	2.7V

Test	S_1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 * V_{CC}
t_{PHZ}/t_{PZH}	GND

Figure 4. Load circuitry for switching times

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

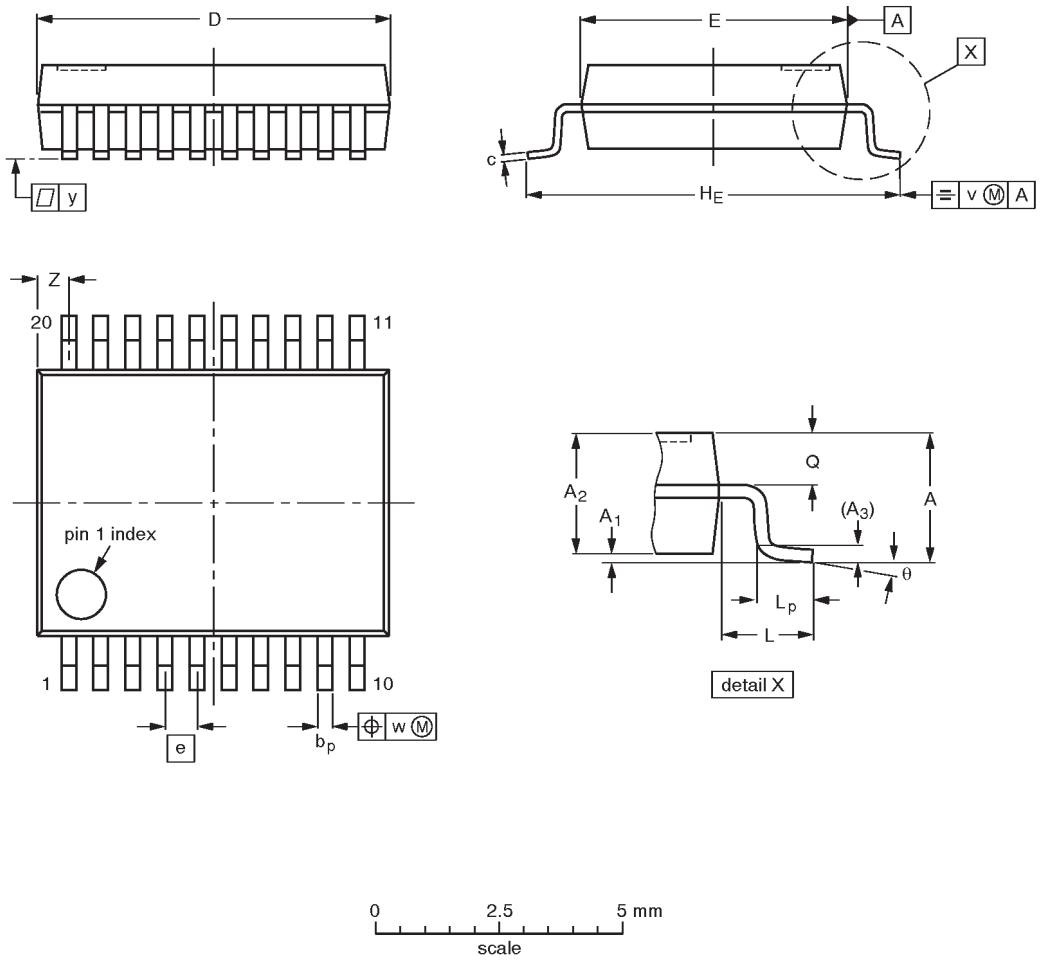
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				~~92-11-17~~ 95-01-24

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**



DIMENSIONS (mm are the original dimensions)

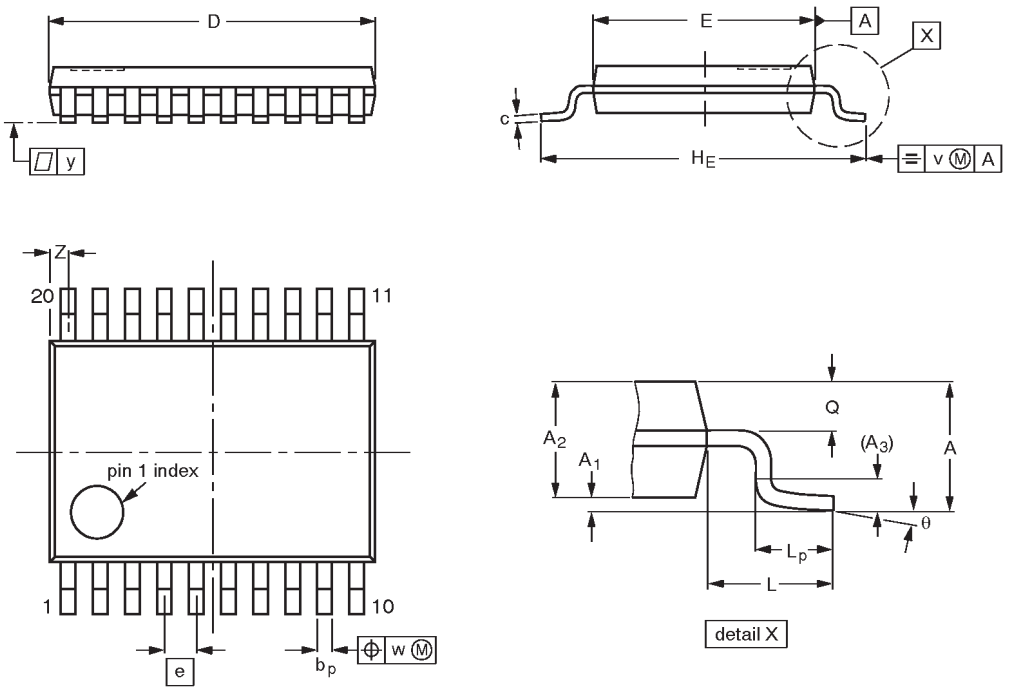
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

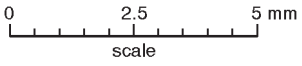
Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				~~93-09-08~~ 95-02-04

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				~~93-06-16~~ 95-02-04

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

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